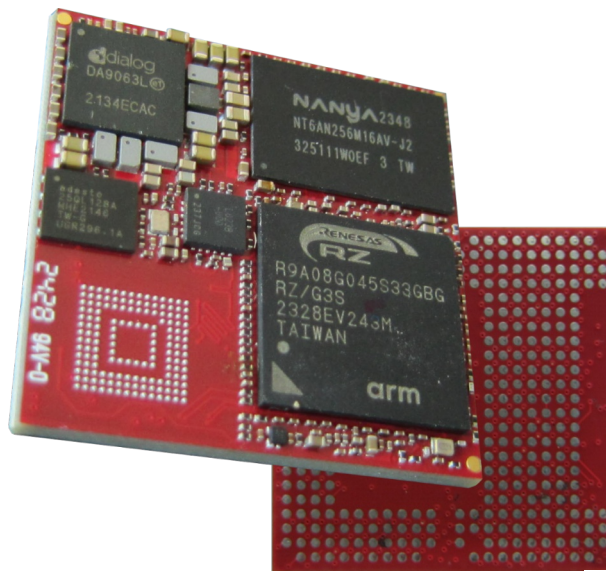# MSRZG3S System In Package

The MSRZG3S is the Open Standard Module (OSM) compliant System-In-Package based on Renesas RZ Family architecture offering high-performance single Cortex-A55 and two Cortex-M33 cores. The MSRZG3S combines compact design and a wide range of services, bringing low power consumption, thermal efficiency and low-cost to embedded systems.
The chosen OSM form factor supports 332 contacts, offers almost all of the CPU functionality on the contacts and is therefore suitable for most industrial applications.

MSRZG3S featureset:

- single Cortex-A55, up to 1.1GHz
- dual Cortex-M33, up to 250MHz
- 512MB – 2GB LPDDR4 RAM
- 4GB eMMC NAND Flash
- dual 10/100/1000MBit Ethernet
- PCIe Gen2 x1
- USB2.0 Host/OTG
- 2x CANFD
- UART, I2C, SPI
- ADC
- compliant to the SGET OSM standard
- size S, 30x30mm²
- pin count: 332
- commercial (-25°C...+85°C) / industrial (-40°C...+85°C) temperature range

(*) Price valid for special configuration and quantity, price does not include VAT or duty

starting (*) EUR 35,00

aries embedded
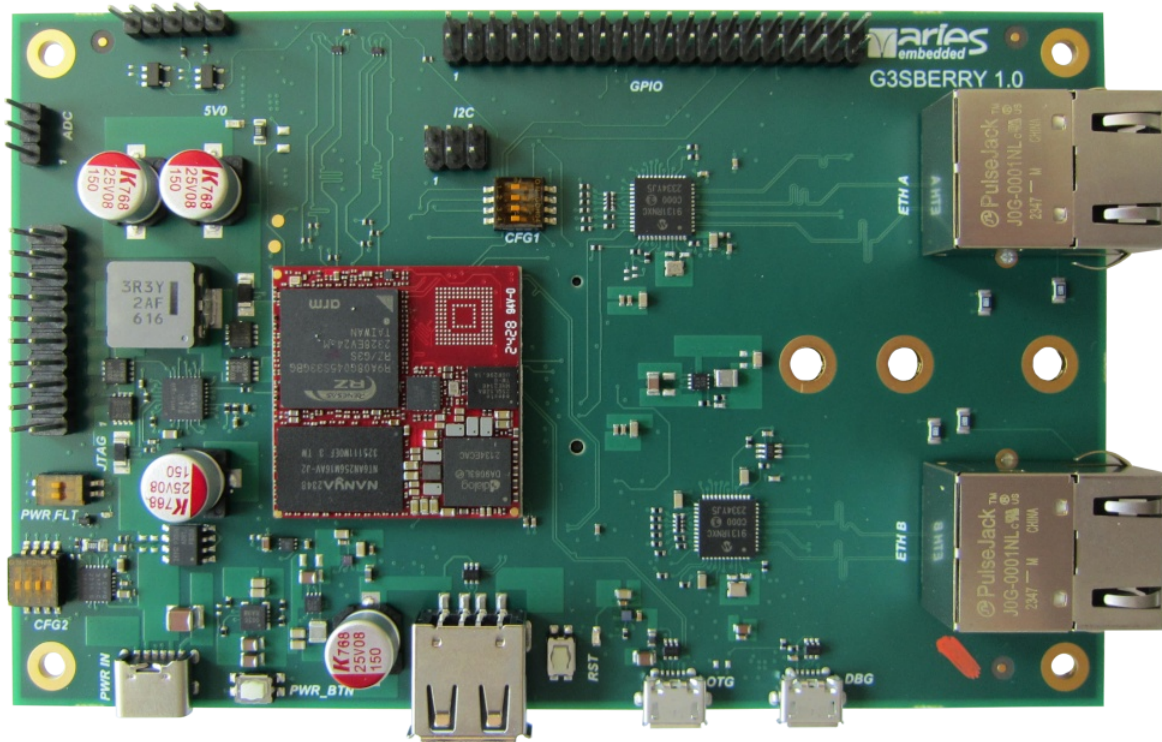*Intelligence for Industry*

ARIES Embedded GmbH
Schöngeisinger Str. 84
D-82256 Fürstenfeldbruck
Germany

Tel: +49(0)8141.36 367-0
Fax: +49(0)8141.36 367-67

www.aries-embedded.com
info@aries-embedded.de

G3SBerry Evaluationboard

The G3SBerry baseboard is build around the MSRZG3S System on Module. The G3SBerry supports users to have a smooth start-up with the new CPU architecture RZ/G3S by Renesas. It supports all necessary features to make first steps with the RZ/G3S CPU, develop and debug drivers and the bootloader and even to use it in prototype setups.

■ G3Berry featureset:

- MSRZG3S-BAA System on Module
  - Renesas RZ/G3S
  - 1GB DDR4 RAM
  - 4GB eMMC
  - 128MBit SPI-NOR
  - -25°...+85°C
- two Ethernet ports 10/100/1000MBit/s on RJ45
- PCIe on M.2 connector
- console via USB to UART
- USB2.0 Host
- USB2.0 OTG
- 2xI2C
- GPIO
- SD-card interface
- 5V single voltage supply via USB